



## Material Content Data Sheet



<b>Sales Product Name</b>				IPD042P03L3 G		<b>Issued</b>		29. August 2013	
<b>MA#</b>				MA000509186					
<b>Package</b>				PG-TO252-3-311		<b>Weight*</b>		315.41 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	4.261	1.35	1.35	13509	13509	
leadframe	non noble metal	iron	7439-89-6	0.143	0.05		454		
	inorganic material	phosphorus	7723-14-0	0.043	0.01		136		
	non noble metal	copper	7440-50-8	143.098	45.35	45.41	453684	454274	
wire	non noble metal	aluminium	7429-90-5	2.769	0.88	0.88	8778	8778	
encapsulation	inorganic material	antimonytrioxide	1309-64-4	1.942	0.62		6158		
	plastics	brominated resin	-	2.081	0.66		6598		
	organic material	carbon black	1333-86-4	2.220	0.70		7038		
	plastics	epoxy resin	-	18.730	5.94		59383		
	inorganic material	silicondioxide	60676-86-0	113.768	36.07	43.99	360695	439872	
leadfinish	non noble metal	tin	7440-31-5	3.740	1.19	1.19	11858	11858	
plating	non noble metal	nickel	7440-02-0	0.086	0.03		274		
	inorganic material	phosphorus	7723-14-0	0.000	0.00	0.03	1	275	
solder	noble metal	silver	7440-22-4	0.083	0.03		264		
	non noble metal	tin	7440-31-5	0.067	0.02		211		
	non noble metal	lead	7439-92-1	3.179	1.01	1.06	10079	10554	
heatspreader	inorganic material	phosphorus	7723-14-0	0.006	0.00		18		
	non noble metal	iron	7439-89-6	0.019	0.01		61		
	non noble metal	copper	7440-50-8	19.177	6.08	6.09	60801	60880	
*deviation	< 10%			Sum in total:		100.00		1000000	

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com